

Application Number 10/731,869
Responsive to Office Action mailed March 8, 2007

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AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0002] with the following amended paragraph:

[0002] The following co-pending and commonly-assigned U.S. Patent Applications, filed on even date herewith, are also incorporated herein by reference in their entirety:

1. U.S. Patent Application Serial No. 10/731,867, entitled "CONCAVITY OF AN IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed on December 9, 2003, assigned Attorney Docket No.: 1023-336US01/P-11800.00;
2. U.S. Patent Application Serial No. 10/731,868, entitled "IMPLANTATION OF LOW-PROFILE IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed on December 9, 2003, assigned Attorney Docket No.: 1023-330US01/P-11795.00;
3. U.S. Patent Application Serial No. 10/731,699, entitled "COUPLING MODULE OF A MODULAR IMPLANTABLE MEDICAL DEVICE," to Darren A. Janzig et al., and filed on December 9, 2003, assigned Attorney Docket No.: 1023-331US01/P-11796.00;
4. U.S. Patent Application Serial No. 10/730,873, entitled "OVERMOLD FOR A MODULAR IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed on December 9, 2003, assigned Attorney Docket No.: 1023-332US01/P-11798.00;
5. U.S. Patent Application Serial No. 10/731,881, entitled "REDUCING RELATIVE INTERMODULE MOTION IN A MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed on December 9, 2003, assigned Attorney Docket No.: 1023-333US01/P-11797.00;
6. U.S. Patent Application Serial No. 10/730,878, entitled "LEAD CONNECTION MODULE OF A MODULAR IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed on December 9, 2003, assigned Attorney Docket No.: 1023-334US01/P-11799.00;

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7. U.S. Patent Application Serial No. 10/730,877, entitled "LOW-PROFILE IMPLANTABLE MEDICAL DEVICE," to Darren A. Janzig et al., and filed on December 9, 2003, assigned Attorney Docket No.: 1023-335US01/P-11801.00; and
8. U.S. Patent Application Serial No. 10/731,638, entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed on December 9, 2003, assigned Attorney Docket No.: P-20542.00.

Please replace paragraph [0039] with the following amended paragraph:

[0039] Once positioned as desired on cranium 12 within the pocket, modular IMD 10 may then be fixed to cranium 12 using an attachment mechanism such as bone screws. The skin flap may be closed over modular IMD 10, and the incision may be stapled or sutured. The location on cranium 12 at which IMD 10 is illustrated as implanted in FIG. 2 is merely exemplary, and IMD 10 can be implanted anywhere on the surface of cranium 12. Further details regarding exemplary techniques for implanting IMD 10 on the cranium may be found in a commonly-assigned U.S. Patent Application Serial No. 10/731,868, entitled "IMPLANTATION OF LOW-PROFILE IMPLANTABLE MEDICAL DEVICE[[],]" ~~assigned Attorney Docket No.: 1023-330US01/P-11795.00.~~

Please replace paragraph [0048] with the following amended paragraph:

[0048] Control module 30 includes control electronics within the housing, e.g., electronics that control the monitoring and/or therapy delivery functions of modular IMD 10, such as a microprocessor. Control module 30 may also include circuits for telemetry communication with external programmers or other devices within the housing. Housing 36 of control module 30 may be hermetic in order to protect the control electronics therein, and in exemplary embodiments is formed of a rigid material, such as titanium, stainless steel, or a ceramic. In exemplary embodiments, housing 36 is a low-profile, concave housing, and techniques for arranging components of control module 30 to enable such a low-profile, concave housing are described in greater detail in a commonly-assigned U.S. Patent Application Serial No.

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10/730,877, entitled "LOW-PROFILE IMPLANTABLE MEDICAL DEVICE[[],]" assigned Attorney Docket No.: 1023-335US01 / P-11801.00.

Please replace paragraph [0051] with the following amended paragraph:

[0051] Housings 36, 38 and 40 may have any shape, including the round, coin shape and rectangular shapes with rounded edges illustrated in FIG. 3. Further, one or more surfaces of one or more of housings 36, 38 and 40 may be concave along at least one axis, and preferably two axes. Further details regarding the concavity of housings 36, 38 and 40 may be found in a commonly-assigned U.S. Patent Application Serial No. 10/731,867, entitled "CONCAVITY OF AN IMPLANTABLE MEDICAL DEVICE[[],]" assigned Attorney Docket No.: 1023-336US01/P-11800.00.

Please replace paragraph [0056] with the following amended paragraph:

[0056] Interconnect member 44 is flexible in a plurality of directions to provide modules 30 and 32 with multiple degrees of freedom of motion with respect to each other. In exemplary embodiments, interconnect member 44 provides at least three degrees of motion, and the degrees of motion provided include rotational motion. Further details regarding the configuration and/or construction of interconnect member 44 to provide such flexibility may be found in a commonly-assigned U.S. Patent Application Serial No. 10/731,699, entitled "COUPLING MODULE OF MODULAR IMPLANTABLE MEDICAL DEVICE[[],]" assigned Attorney Docket No.: 1023-331US01 / P-11796.00.

Please replace paragraph [0058] with the following amended paragraph:

[0058] Overmold 48 can be shaped to contour to cranium 12, e.g., may be concave along at least one axis, and may be contoured at its edges to prevent skin erosion on the scalp of patient 14. The flexibility and shape of overmold 48 may improve the comfort and cosmetic appearance of modular IMD 10 under the scalp. Further details regarding the overmold, the concavity of the flexible overmold, and techniques for restricting intermodular motion in a modular IMD 10 may be found in a commonly-assigned U.S. Patent Application Serial No. 10/730,873, entitled "OVERMOLD FOR A MODULAR IMPLANTABLE MEDICAL DEVICE," assigned Attorney

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Docket No.: 1023-332US01 / P-11798.00, and a commonly-assigned U.S. Patent Application Serial No. 10/731.881, entitled "REDUCING RELATIVE INTERMODULE MOTION IN A MODULAR IMPLANTABLE MEDICAL DEVICE[[],]" assigned Attorney Docket No.: 1023-333US01 / P-11797.00.

Please replace paragraph [0062] with the following amended paragraph:

[0062] In some embodiments, control module 30 includes telemetry circuitry 64, which enables processor 60 to communicate with other devices such as an external programming device via radio-frequency communication. Telemetry circuitry 64 may include a telemetry coil (not illustrated), which may be fabricated of windings of copper or another highly conductive material. The configuration and location of telemetry coil within housing 36 may be dictated by the available space within housing 36 and the communication requirements of telemetry circuitry 64. Further detail regarding the configuration and location of the telemetry coil may be found in a commonly-assigned U.S. Patent Application Serial No. 10/730.877, entitled "LOW-PROFILE IMPLANTABLE MEDICAL DEVICE[[],]" assigned Attorney Docket No.: 1023-335US01 / P-11801.00.

Please replace paragraph [0075] with the following amended paragraph:

[0075] FIG. 11B illustrates a side-profile of modular IMD 140. Housing 142 may be a low-profile housing with a thickness 146 that is approximately less than or equal to 6 millimeters. Techniques for arranging components of an IMD to enable a low-profile housing may be found in the commonly-assigned U.S. Patent Serial No. 10/730.877, entitled "LOW-PROFILE IMPLANTABLE MEDICAL DEVICE[[],]" assigned Attorney Docket No.: 1023-335US01 / P-11801.00.. A low-profile housing 142 may allow modular IMD 140 to be implanted, for example, within an upper buttocks region of patient 14.